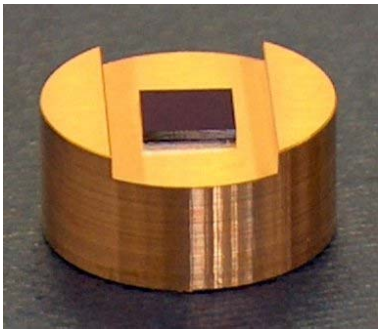
Soldered SAM data sheet SAM-λ-A-12.7s

GaAs chip area	standard:	4mm x 4mm
	optional:	other dimensions on request
Chip thickness	standard:	400 µm
	optional:	150 µm
Front side protection	the SAM is protected with a dielectric front layer.	

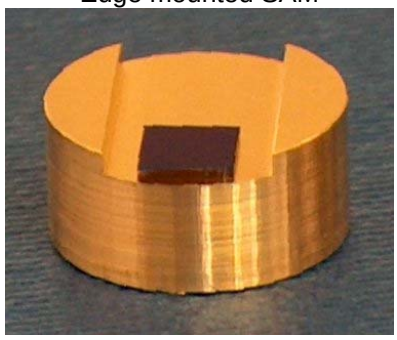
The SAM chip is soldered on a gold plated Cu-cylinder with 12.7 mm Ø using a Sn/Bi solder. The solder provides a low thermal resistance between the SAM and the mount.

- The ***standard*** position of the SAM is at the center of the mount.
- ***Optional*** the SAM can be soldered on the edge of the mount without extra charges.

Center mounted SAM

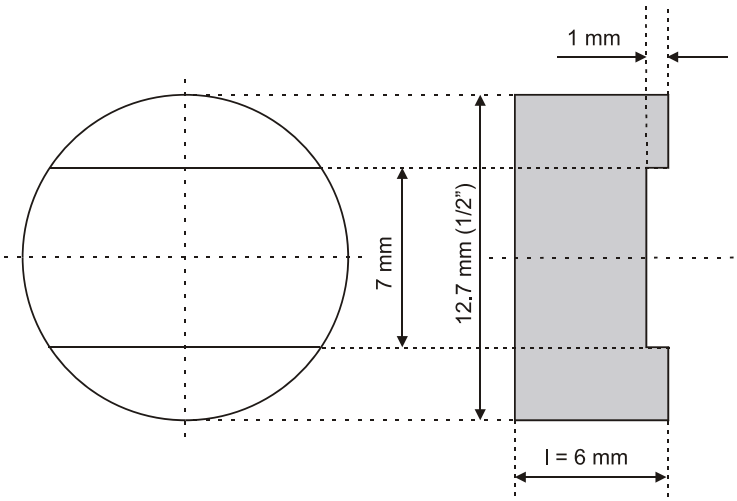


Edge mounted SAM



Mount

Cu-cylinder, ∅ = 12.7 mm
l = 6.0 mm



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